

PATENT ASSIGNMENT COVER SHEET

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Assignment ID: PATI296129

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
SEQUENCE:	2	
CONVEYING PARTY DATA		
	Name	Execution Date
	Tech Mahindra (Shanghai) Co. Ltd.	05/14/2019
RECEIVING PARTY DATA		
Company Name:	Medtronic Engineering and Innovation Center Private Limited	
Street Address:	3rd & 4th Floor, Block-1, BSR IT/ITES SEZ	
Internal Address:	Nanakramguda Village, Serilingampally Mandal	
City:	Hyderabad, Ranga Reddy, Telangana	
State/Country:	INDIA	
Postal Code:	500008	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	17306994	
CORRESPONDENCE DATA		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	2034925000	
Email:	rs.patents.two@medtronic.com	
Correspondent Name:	Carolynn Knight	
Address Line 1:	60 Middletown Avenue	
Address Line 4:	north haven, CONNECTICUT 06473	
ATTORNEY DOCKET NUMBER:	C00015404US02DIV	
NAME OF SUBMITTER:	Carolynn Knight	
SIGNATURE:	Carolynn Knight	
DATE SIGNED:	06/13/2024	
	This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 4		
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DEED OF ASSIGNMENT

This Deed of Assignment is executed by:

TECH MAHINDRA (SHANGHAI) CO. LTD., having its registered office at Gateway Building, Apollo Bunder, Mumbai- 400001, India, and its representatives and affiliates (hereinafter referred to as “Assignor”);

and, **Medtronic Engineering and Innovation Center Private Limited**, having offices at Address: 3rd & 4th Floor, Block-1, BSR IT/ITES SEZ, Nanakramguda Village, Serilingampally Mandal, Hyderabad, Ranga Reddy, Telangana, 500008 India (hereinafter referred to as “Assignee”).

WHEREAS, Assignor and Assignee entered into an Engineering Development Agreement dated August 22, 2012;

WHEREAS the Engineering Development Agreement transferred and assigned, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, all right, title and interest in any and all intellectual property, trade secrets and knowledge, including but not limited to methods, ideas, apparatuses, compositions, drawings, abstracts, specifications, inventions, written material, audiovisual material, formulas, data, computer software and rights related thereto, including but not limited to copyrights, trademarks, patents, patent applications, trade secrets, and other properties developed by Assignor or Assignee under the Engineering Development Agreement either jointly or individually (“Intellectual Property”);

WHEREAS, Assignor hereby acknowledges, by virtue of the Engineering Development Agreement, Assignor transferred to Assignee all right, title and interest in and to the inventions and applications (including any continuations, continuations-in-part, divisionals, RCE’s or other parent or child applications or inventions) and to all foreign counterparts thereof (including patent, utility model and industrial designs), as listed on the attached *Schedule A*, and in and to any Letters Patent and Registrations which may hereafter be granted on any patent applications claiming priority from the same in the United States and all countries throughout the world, and to claim the priority from the applications as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee’s successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignor had this Deed of Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof;

WHEREAS Assignor desires to ensure to that to the extent any of Assignor’s right, title and interest in the foregoing Intellectual Property, including the patents and applications listed on the attached *Schedule A*, are deemed not transferred from Assignor to Assignee, that any such past, present and future rights, title and interest in the foregoing Intellectual Property be presently assigned to Assignee.

[CONTINUED ON NEXT PAGE]

NOW, THEREFORE, the parties agree as follows:

ASSIGNOR: TECH MAHINDRA (SHANGHAI) CO. LTD.

Hereby sells, assigns and transfers to

ASSIGNEE: Medtronic Engineering and Innovation Center Private Limited


And the successors, assigns and legal representatives of the ASSIGNEE any and all rights, title and interest ASSIGNOR may have, if any, including the right to sue for present, past and future infringement, in the United States, its territorial possessions, and in all foreign countries, including all treaty and convention rights, the Intellectual Property, including the inventions and applications (including any continuations, continuations-in-part, divisionals, RCE's or other parent or child applications or inventions) and to all foreign counterparts thereof (including patent, utility model and industrial designs), as listed on the attached *Schedule A*, and in and to any Letters Patent and Registrations which may hereafter be granted on any patent applications claiming priority from the same in the United States and all countries throughout the world, and to claim the priority from the applications as provided by the Paris Convention.

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IN TESTIMONY WHEREOF, Assignor has signed his name on the date indicated.

TECH MAHINDRA (SHANGHAI) CO. LTD.

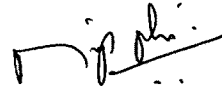
**Medtronic Engineering and Innovation
Center Private Limited**



Printed Name: Mohammad Rafeeq

Title: Delivery Manager

Dated: 14th MAY 2019



Printed Name: Divya Prakash Joshi

Title: Sr. Engineering Director

Dated: 16-April-2021

WITNESS



Printed Name: Anirudh Raikar

Dated: 14th may 2019

WITNESS



Printed Name: K V S Manoj Kumar Vadali

Dated: 16- April-2021

Schedule A

Docket Number	Filing Date/Filed on date	Application No.	Title
C00014823.WOU1	2017-06-08	PCT/CN2017/087519	CIRCULAR STAPLING INSTRUMENT
C00015403.WOU1	2017-09-01	PCT/CN2017/100233	CIRCULAR STAPLING DEVICE WITH POSITION RIBS
C00017291.WOU1	2018-12-06	PCT/CN2018/119480	ANVIL ASSEMBLY WITH IMPROVED CUT RING ASSEMBLY
C00015404.USP1	2017-11-28	<u>62/591,735</u>	SURGICAL STAPLING INSTRUMENT AND ASSOCIATED TRIGGER MECHANISMS
C00015404US01	2018-11-02	16/179,039	SURGICAL STAPLING INSTRUMENT AND ASSOCIATED TRIGGER MECHANISMS